

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	55	(Sputtering vacuum adj2 deposition) near5 polishing with (circuit wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 10:52
L2	8	(Sputtering vacuum adj2 deposition) near5 roughness with (circuit wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 10:55
L3	183	(Sputtering vacuum adj2 deposition evaporation) with (reduc\$3 decreas\$3) near5 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 10:57
L4	69	(Sputtering vacuum adj2 deposition evaporation) with (reduc\$3 decreas\$3) near5 surface adj roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 10:57
L5	0	(Sputtering vacuum adj2 deposition evaporation) with (reduc\$3 decreas\$3) near5 surface adj roughness same foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:04
L6	22	("20020060090" "20020155021" "20030006063" "20030096082" "20030108766" "4959507" "5273938" "6309528" "6476330" "6558231" "6750144").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:15

L7	387	Multilayer near2 laminate and circuit adj board and laminating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:17
L8	3	Multilayer near2 laminate and circuit adj board and laminating and (reduc \$3 decreas\$3) near5 surface adj roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:17
L9	64	circuit adj board and laminating and (reduc \$3 decreas\$3) near5 surface adj roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:19
L10	114	Circuit adj (pattern trace) and Multilayer near2 laminate and circuit adj board and laminating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:20
L11	788	(Sputtering vacuum adj2 deposition evaporation) with copper adj foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:45
L12	34	(Sputtering vacuum adj2 deposition evaporation) with copper adj foil with roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:45
L13	75	(Sputtering vacuum adj2 deposition evaporation) with surface near5 copper adj foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:46
L14	2	(Sputtering vacuum adj2 deposition evaporation) with surface near5 copper adj foil same roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:57

L15	52	(Sputtering vacuum adj2 deposition evaporation) with copper adj foil same roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:57
L16	34	(Sputtering vacuum adj2 deposition evaporation) with copper adj foil with roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 11:57
L17	178	(Sputtering vacuum adj2 deposition evaporation) with (reduc\$3 decreas\$3) with surface adj roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/07/08 12:01

EAST Search History (I nterference)

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polishing circuit trace.wsp